LOP/SLP - Series 2,54mm pitch

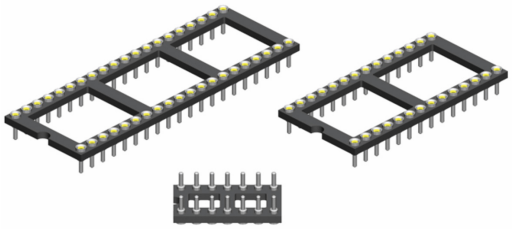
"low profile" Sockets & Strips

RoHS 2002/95/EC compliant

E-tec Interconnect

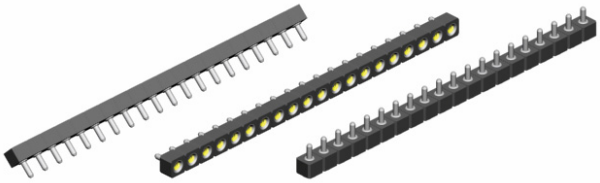
Low profile DIP sockets LOP Series

height above PCB 2.41mm / .095"

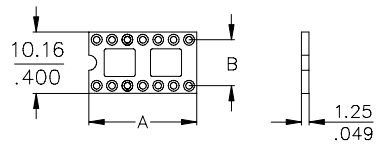


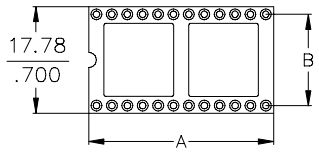
Low profile strips SLP Series

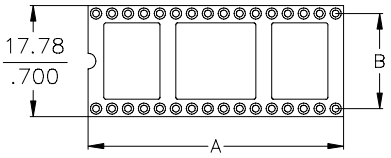
height above PCB 2.41mm / .095"

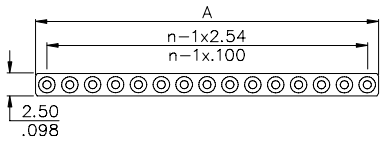


Insulator









Pin	Dimensions mm/inch "A"	"B"	Ordering Code
14	17,78/.700	7,62 .300	LOP - 314 - S083 - 95
16	20,32/.800		LOP - 316 - S083 - 95
18	22,86/.900		LOP - 318 - S083 - 95
20	25,40/1.000		LOP - 320 - S083 - 95
24	30,48/1.200		LOP - 324 - S083 - 95
24	30,48/1.200	15,24 .600	LOP - 624 - S083 - 95
28	35,56/1.400		LOP - 628 - S083 - 95
32	40,64/1.600	15,24 .600	LOP - 632 - S083 - 95
40	50,80/2.000		LOP - 640 - S083 - 95
10	25,40/1.000		SLP - 110 - S083 - 95
14	35,56/1.400		SLP - 114 - S083 - 95
Other sizes on request.			

Pin-outs

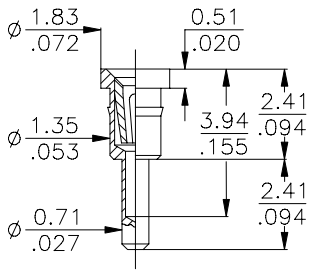
Other pin-outs available on request.

Despite the very low profile of these sockets the IC legs can be inserted completely.

Recommended PCB Layout

Recommended drilling hole dia ∅ 0,8mm/.031"

Low Profile Terminal



083 2.41mm / .095" over PCB

Plating

Standard:

- **95** = tin/gold *(tin leadfree)*

Alternative

- **55** = gold/gold
- **99** = tin/ tin *(leadfree)*

Specifications

Mechanical data

Insertion force	1,80 N (avg)
Extraction force	0,90 N (avg)
Contact life	> 100 cycles
Solderability	exceeds MIL-STD-202 Methode 208
Water absorbtion during 24hrs at 20°C	0,05%
Contact security:	
-Vibration (MIL-STD-202 Method 204 B)	20g
-Shock (MIL-STD-202 Method 202 C)	150g

Material

Insulator *(RoHS compliant)*	std. temp PBT plastic UL 94 V-0
Terminal *(RoHS compliant)*	CuZn
Contact *(RoHS compliant)*	BeCu

Electrical data

Contact resistance at 1A	4,3 mΩ typ.
Current rating	1A max., 100V
Contact capacitance at 1MHz	2 pF max.
Insulation resistance at 500V DC (MIL-STD-1344 Methode 3003)	5×10^9 Ω min.
Breakdown voltage at 60 Hz (MIL-STD-1344 Methode 3001.1)	500 V AC
Contact resistance	≤7 mΩ
Operating temperature	-55° C to +125° C
Pitch	2,54 mm (.100")